

900V N-Channel Silicon Carbide Power MOSFET

FEATURES

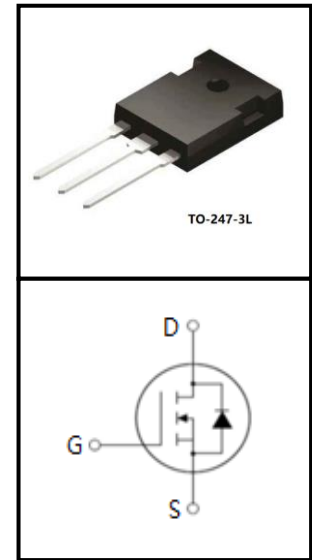
- Low On-Resistance
- Low Capacitance
- Avalanche Ruggedness
- Halogen Free, RoHS Compliant

BENEFITS

- Higher System Efficiency
- Parallel Device Convenience
- High Temperature Application
- High Frequency Operation

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Power Factor Correction (PFC)
- Uninterruptible Power Supply (UPS)
- EV Charging station & Motor Drives
- Solar/ Wind Renewable Energy
- Power Inverters & DC/DC Converters



Device Marking and Package Information

Device	Package	Marking
C2M090W035	TO-247-3L	C2M090W035

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value	Unit
Drain-Source Voltage	V_{DS}	$V_{GS}=0V, I_{DS}=100\mu A$	900	V
Continuous Drain Current	I_D	$V_{GS}=20V, T_C=25^\circ\text{C}$	80	A
Pulsed Drain Current	I_{DM}	t_{PW} limitation per Fig.17	320	
Power Dissipation	P_D	$T_C=25^\circ\text{C}$	338	W
Recommend Gate Source Voltage	$V_{GS, op}$	Static	-5/+20	V
Maximum Gate Source Voltage	$V_{GS, max}$	AC ($f > 1\text{Hz}$)	-10/+25	
Soldering Temperature	T_L		260	$^\circ\text{C}$
Operating Junction and Storage Temperature Range	T_J, T_{stg}		-55/+150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	0.37	K/W

Specifications $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 100μA	900	--	--	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 900V, V _{GS} = 0V, T _J = 25°C	--	<1	100	μA
		V _{DS} = 900V, V _{GS} = 0V, T _J = 150°C	--	10	500	
Gate-Source Leakage	I _{GSS}	V _{GS} = 20V, V _{DS} = 0V	--	--	200	nA
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = 10V, I _D = 20mA	2	--	3.5	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 20V, I _D = 40A	--	35	42	mΩ
Dynamic						
Input Capacitance	C _{iss}	V _{GS} = 0V V _{DS} = 600V f = 1.0MHz V _{AC} =25mV	--	2316	--	pF
Output Capacitance	C _{oss}		--	180	--	
Reverse Transfer Capacitance	C _{rss}		--	26	--	
Effective Output Capacitance, Energy Related	Co(er)	V _{GS} =0V V _{DS} =0 to 600V		187		
Effective Output Capacitance, Time Related	Co(tr)	I _D =const., V _{GS} =0V V _{DS} =0 to 600V		253		
Total Gate Charge	Q _g	V _{DS} =400V, V _{GS} =0/+15V, I _D =40A	--	170	--	nC
Gate-Source Charge	Q _{gs}		--	29	--	
Gate-Drain Charge	Q _{gd}		--	80	--	
Gate plateau voltage	V _{pl}		--	10.3	--	V
Turn-on Delay Time	t _{d(on)}	V _{DS} =400V V _{GS} =0/15V I _D =40A RG(ext)= 2.5Ω	--	45	--	ns
Turn-on Rise Time	t _r		--	103	--	
Turn-off Delay Time	t _{d(off)}		--	66	--	
Turn-off Fall Time	t _f		--	18	--	
Coss Stored Energy	E _{oss}	V _{GS} =0V, V _{DS} =900V f =1MHz, V _{AC} =25mV	--	119	--	μJ
Turn-on Switching Energy	E _{on}	V _{DS} =900V, V _{GS} =0/15V, I _D =40A, RG(ext)= 2.5Ω	--	194*	--	
Turn-off Switching Energy	E _{off}		--	326*	--	
Internal Gate Resistance	RG(int.)	f =1MHz, V _{AC} =25mV	--	3	--	Ω

*Base on the results of calculation, note that the energy loss caused by the reverse recovery of FWD is not included in E_{on} .

Built-in SiC Diode Characteristics						
Continuous Diode Forward Current	I_S	$V_{GS} = 0V$	--	80	--	A
Inverse Diode Forward Voltage	V_{SD}	$I_{SD} = 24A, V_{GS} = -5V$	--	--	6	V
Reverse Recovery Time	t_{rr}	$I_F = 20A, V_{DS}=180V,$ $di_F/dt = 500A/\mu s$	--	27	--	ns
Reverse Recovery Charge	Q_{rr}		--	73	--	nC
Peak Reverse Recovery Current	IRM		--	4.5	--	A

Typical Device Performance

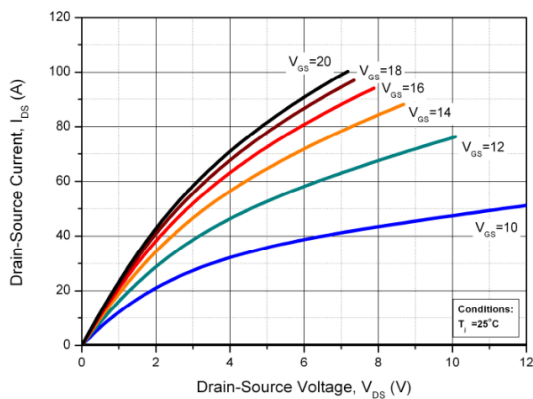


Fig. 1 Forward Output Characteristics at $T_j = 25^\circ C$

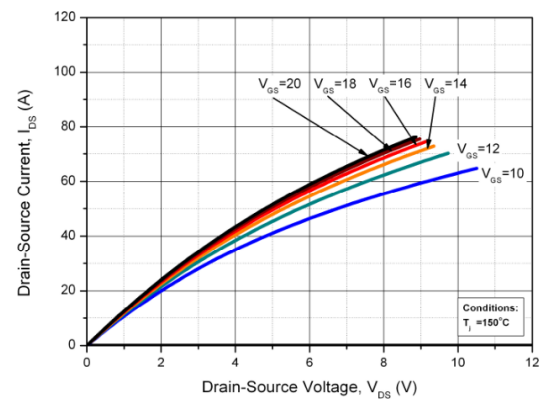


Fig. 2 Forward Output Characteristics at $T_j = 150^\circ C$

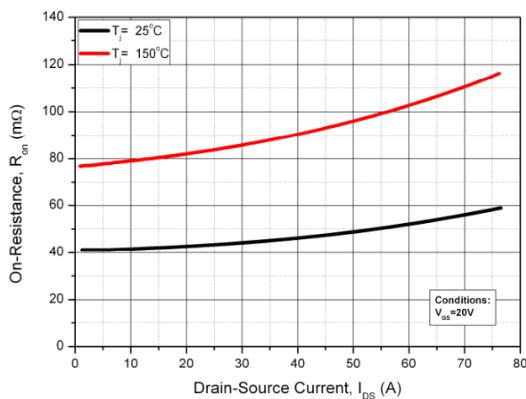


Fig. 3 On-Resistance vs. Drain Current for Various T_j

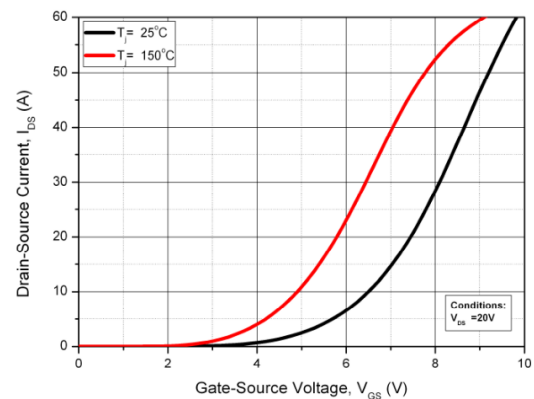


Fig. 4 Transfer Characteristics for Various T_j

Typical Device Performance

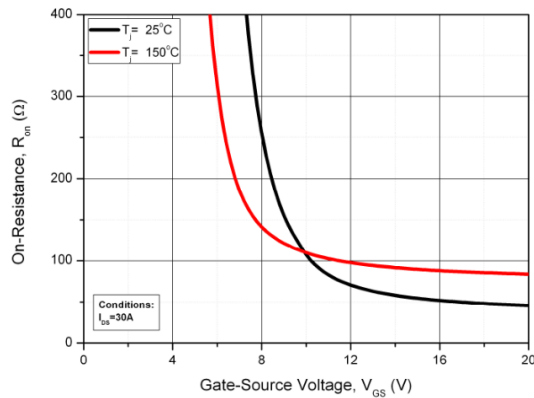


Fig. 5 On-Resistance vs. Gate Voltage for Various T_j

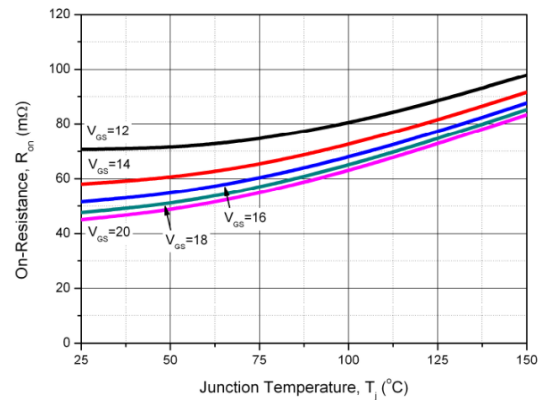


Fig. 6 On-Resistance vs. Temperature for Various Gate Voltage

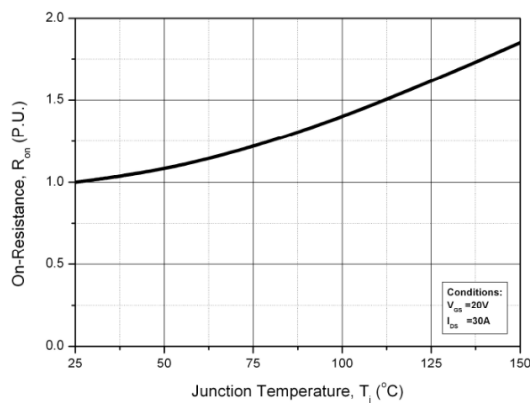


Fig. 7 Normalized On-Resistance vs. Temperature

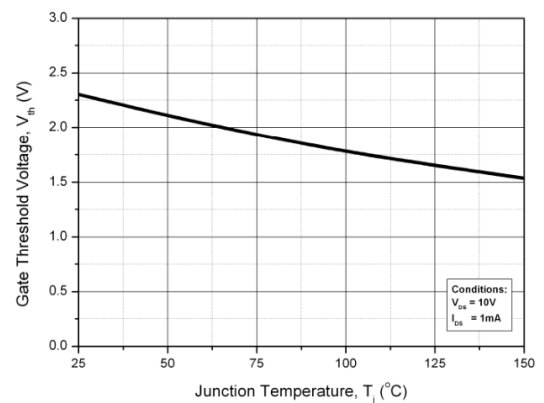


Fig. 8 Threshold Voltage vs. Temperature

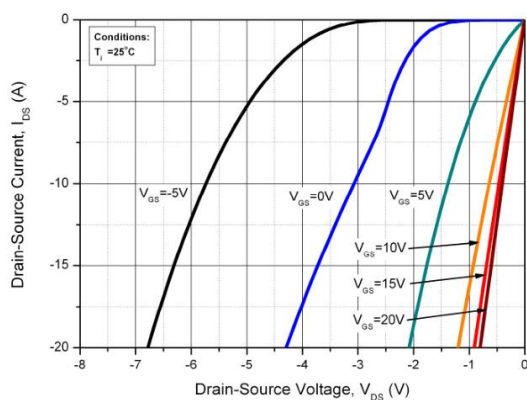


Fig. 9 Reverse Output Characteristics at $T_j = 25^\circ\text{C}$

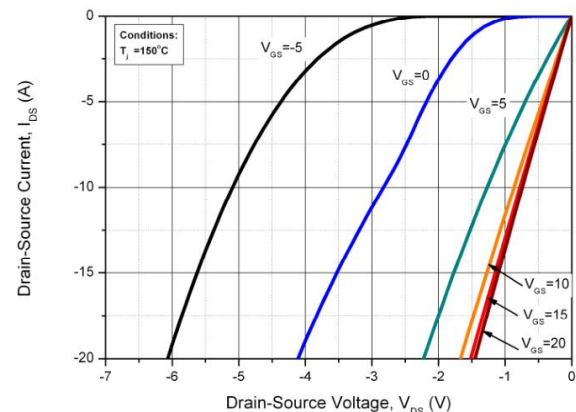


Fig. 10 Reverse Output Characteristics at $T_j = 150^\circ\text{C}$

Typical Device Performance

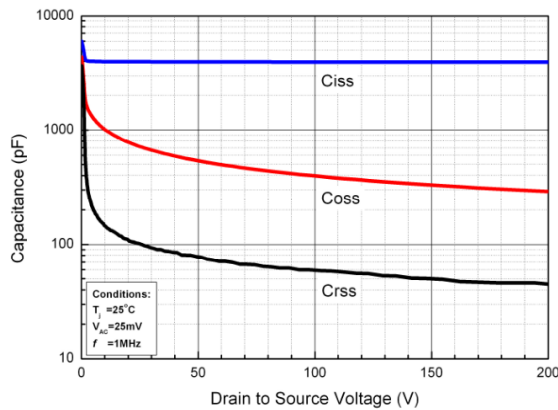


Fig. 11 Capacitances vs. Drain to Source Voltage (0 - 200V)

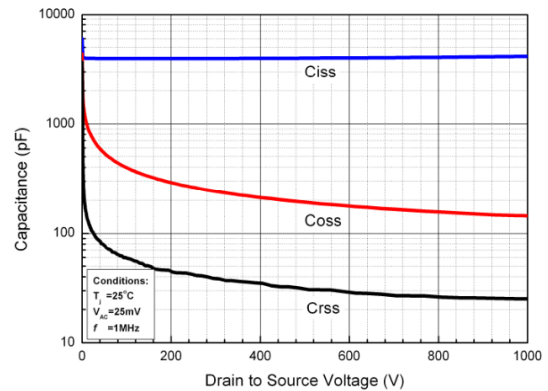


Fig. 12 Capacitances vs. Drain to Source Voltage (0 - 1000V)

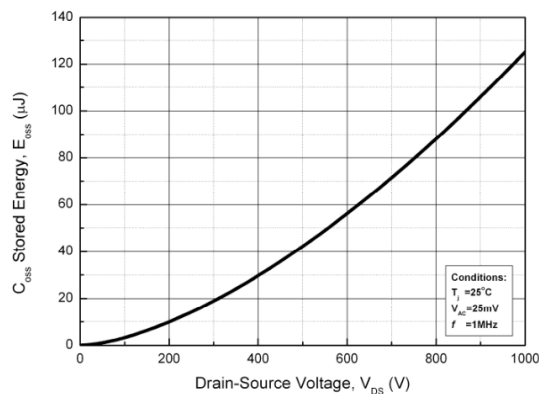


Fig. 13 Output Capacitor Stored Energy

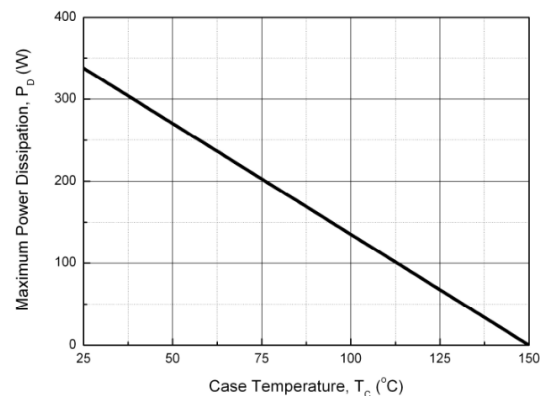


Fig. 14 Maximum Power Dissipation Derating vs. Case Temperature

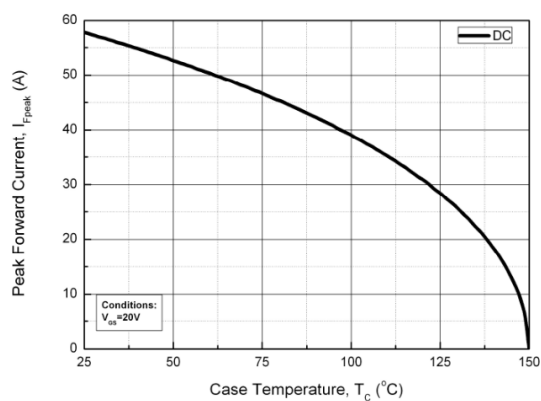


Fig. 15 Drain Current Derating vs. Case Temperature

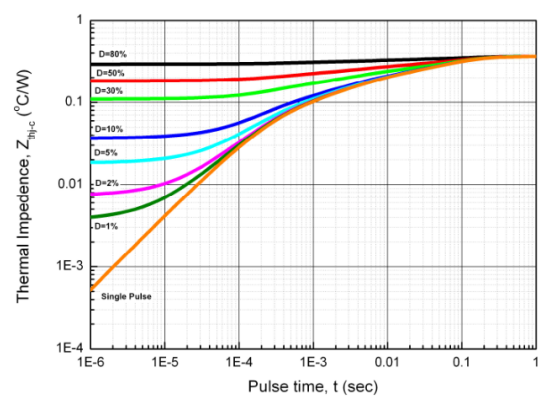


Fig. 16 Transient Junction to Case Thermal Impedance

Typical Device Performance

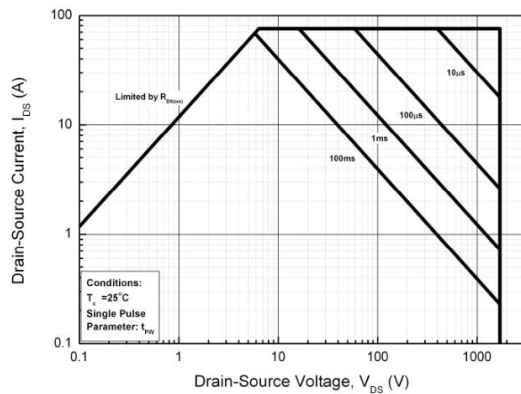


Fig. 17 Safe Operating Area

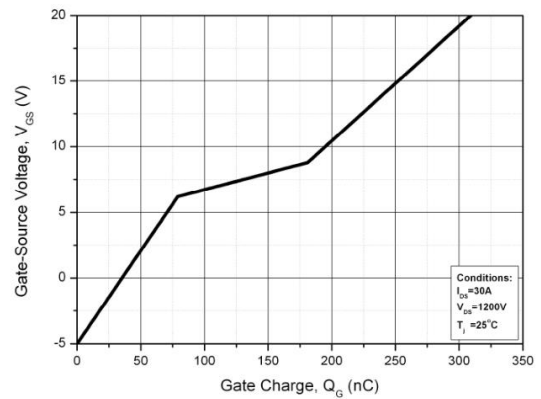


Fig. 18 Gate Charge Characteristics

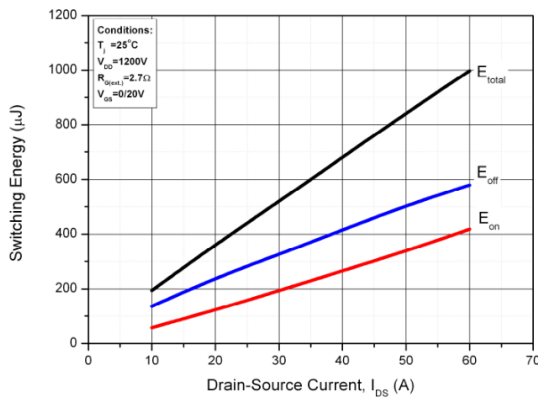


Fig. 19 Clamped Inductive Switching Energy vs. Drain Current ($V_{DS}=1200\text{V}$)*

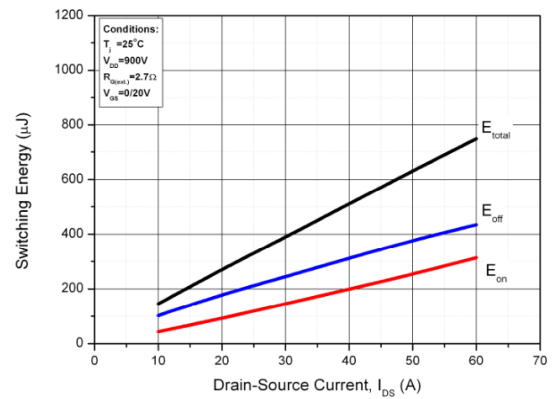


Fig. 20 Clamped Inductive Switching Energy vs. Drain Current ($V_{DS}=900\text{V}$)*

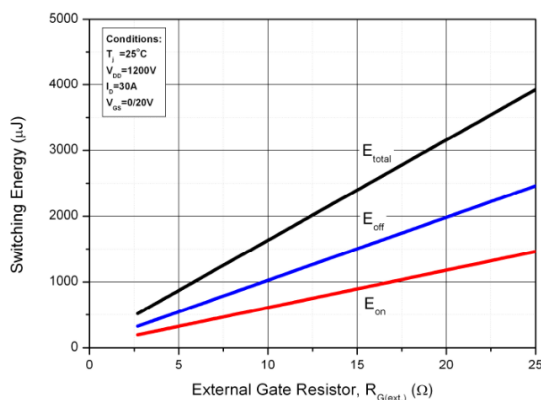
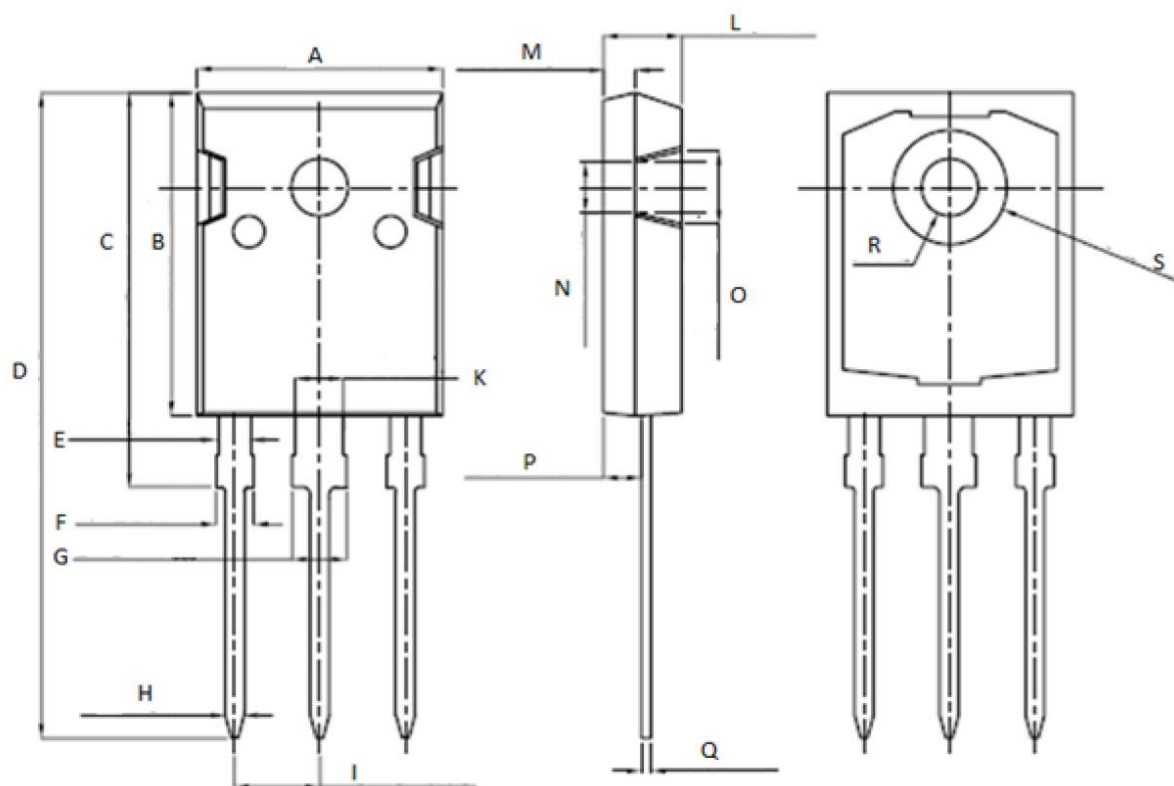


Fig. 21 Clamped Inductive Switching Energy vs. External Gate Resistor ($R_{G(ext.)}$)*

*Base on the results of calculation, note that the energy loss caused by the reverse recovery of FWD is not included in E_{on} .

TO-247



Unit: mm		
Symbol	Min.	Max.
A	15.95	16.25
B	20.85	21.25
C	20.95	21.35
D	40.5	40.9
E	1.9	2.1
F	2.1	2.25
G	3.1	3.25
H	1.1	1.3
I	5.40	5.50

Unit: mm		
Symbol	Min.	Max.
K	2.90	3.10
L	4.90	5.30
M	1.90	2.10
N	4.50	4.70
O	5.40	5.60
P	2.29	2.49
Q	0.51	0.71
R	φ 3.5	φ 3.7
S	φ 7.1	φ 7.3

*The information provided herein is subject to change without notice.

Disclaimer

All product specifications and data are subject to change without notice.

For documents and material available from this datasheet, Suzhou Convert does not warrant or assume any legal liability or responsibility for the accuracy, completeness of any product or technology disclosed hereunder.

No license, express or implied, by estoppels or otherwise, to any intellectual property rights is granted by this document or by any conduct of Suzhou Convert.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless. Customers using or selling Suzhou Convert products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Suzhou Convert for any damages arising or resulting from such use or sale.

Suzhou Convert disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Suzhou Convert's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

Suzhou Convert Semiconductor CO., Ltd. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

In the event that any or all Suzhou Convert products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. Suzhou Convert believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [MOSFET](#) category:

Click to view products by [Convert Semiconductor](#) manufacturer:

Other Similar products are found below :

[614233C](#) [648584F](#) [MCH3443-TL-E](#) [MCH6422-TL-E](#) [FDPF9N50NZ](#) [FW216A-TL-2W](#) [FW231A-TL-E](#) [APT5010JVR](#) [NTNS3A92PZT5G](#)
[IRF100S201](#) [JANTX2N5237](#) [2SK2464-TL-E](#) [2SK3818-DL-E](#) [FCA20N60_F109](#) [FDZ595PZ](#) [STD6600NT4G](#) [FSS804-TL-E](#) [2SJ277-DL-E](#)
[2SK1691-DL-E](#) [2SK2545\(Q,T\)](#) [D2294UK](#) [405094E](#) [423220D](#) [MCH6646-TL-E](#) [TPCC8103,L1Q\(CM](#) [367-8430-0972-503](#) [VN1206L](#)
[424134F](#) [026935X](#) [051075F](#) [SBVS138LT1G](#) [614234A](#) [715780A](#) [NTNS3166NZT5G](#) [751625C](#) [873612G](#) [IRF7380TRHR](#)
[IPS70R2K0CEAKMA1](#) [RJK60S3DPP-E0#T2](#) [RJK60S5DPK-M0#T0](#) [APT5010JVFR](#) [APT12031JFLL](#) [APT12040JVR](#) [DMN3404LQ-7](#)
[NTE6400](#) [JANTX2N6796U](#) [JANTX2N6784U](#) [JANTXV2N5416U4](#) [SQM110N05-06L-GE3](#) [SIHF35N60E-GE3](#)